

FlipChip International Appoints Bruce Bowers as Vice President of Operations

PHOENIX, Arizona, March 5, 2004---FlipChip International, LLC announced today that it has appointed Bruce Bowers as its Vice President of Operations for its semiconductor wafer scale packaging and bumping business in Phoenix, Arizona.

Prior to joining FlipChip International, Mr. Bowers has demonstrated significant leadership and operational experience in his 36 years in the semiconductor and wafer scale packaging industry. Mr. Bowers' experience includes high performance analog package/product development management at Texas Instruments' operations in Tucson, Arizona, operations management at Burr Brown Corporation, sales management at Amkor, and semiconductor package engineering at Motorola.

Bob Forcier, President and CEO of FlipChip International, stated, "We are pleased to have Bruce Bowers join FlipChip International as the Vice President of Operations. Bruce compliments our key management team by bringing a unique blend of related knowledge to our business. Bruce's extensive experience in the areas of manufacturing, semiconductor package engineering, and cleanroom operations will accelerate our current capacity expansions in Phoenix, Arizona. Bruce also has performed in international business operations that will provide strengths in our world wide customer support as flip chip technologies continue to accelerate in growth and adoption in next generation products such as smart phones and wireless devices."

Mr. Bowers said, "I am delighted to join the FlipChip International team of professionals. I see a very skilled and willing workforce that will provide best in class services for the current wafer scale packaging and wafer bumping services. I am also very excited with the FlipChip International potential for future growth in new products."

Mr. Bowers earned an Electronics Technology degree from United Electronics Institute in Louisville, Kentucky.

FlipChip International, LLC is a private supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. FlipChip International, LLC is a wholly owned subsidiary of RoseStreet Labs, LLC, a supplier of products and services for wireless infrastructure in the life science and homeland security markets.

For further information contact:

Stephanie Sarabia
FlipChip International
602-431-6020 x216
ssarabia@flipchip.com